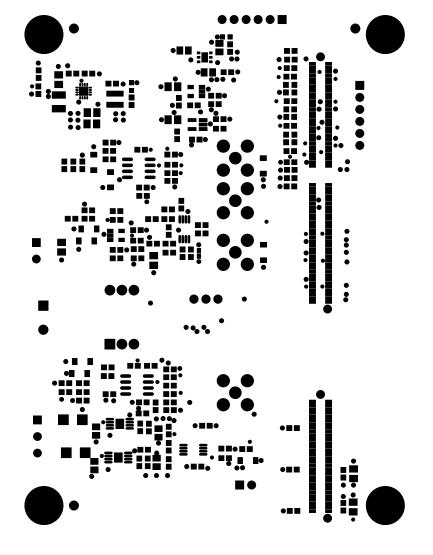
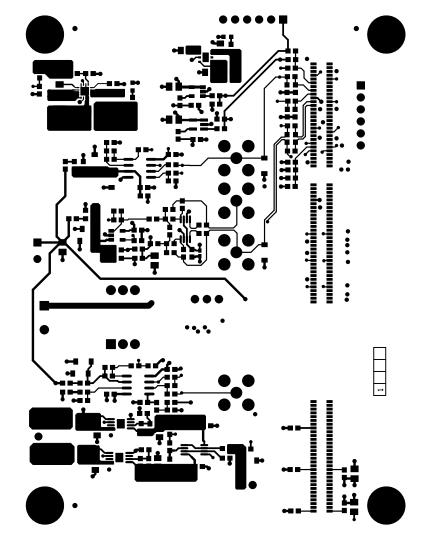


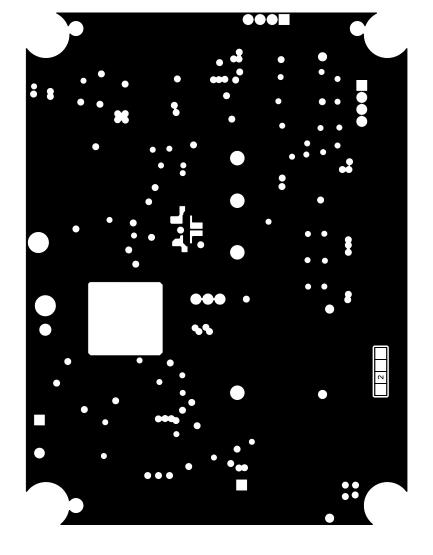
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00316	REV: E2	SUN REU	: Not In VersionControl
LAYER NAME = Top Overlay				
TIDA-00316_E2.GT0	GENERATED : 6/12/2	2015 4:11:17	PM	TEXAS INSTRUMENTS



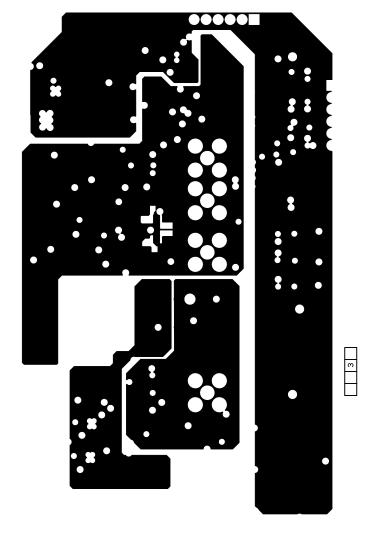
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00316	REV: E2	SUN REU: N	Not In VersionControl
LAYER NAME = Top Solder				
TIDA-00316_E2.GTS	GENERATED : 6/12/2	2015 4:11:17	PM	TEXAS INSTRUMENTS



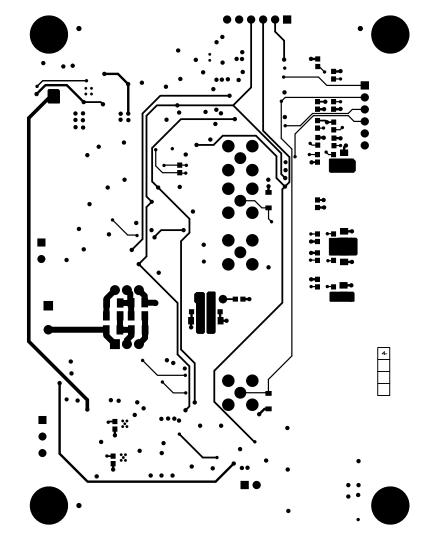
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00316	REV: E2	SUN REV	Not In VersionControl
LAYER NAME = Top Layer				
TIDA-00316_E2.GTL	GENERATED : 6/12/2	2015 4:11:16	PM	TEXAS INSTRUMENTS



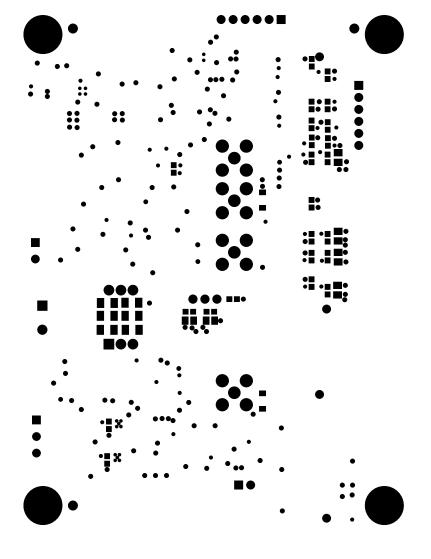
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00316	REU: E2	SUN REU: 1	Not In VersionControl
LAYER NAME = L1_GND				
TIDA-00316_E2.G1	GENERATED : 6/12/2	2015 4:11:16	PM	TEXAS INSTRUMENTS



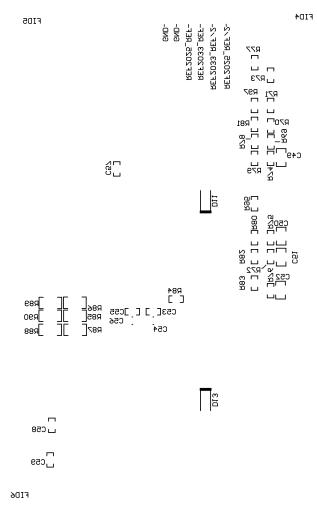
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00316	REV: E2	SUN REU:	Not In VersionControl
LAYER NAME = L2_POWER				
TIDA-00316_E2.G2	GENERATED : 6/12/2	2015 4:13:31	PM	TEXAS INSTRUMENTS



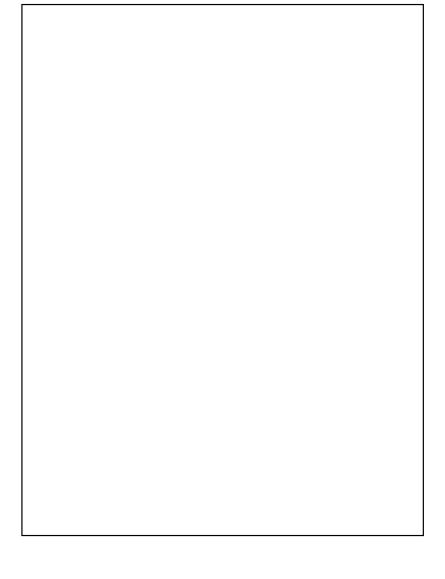
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00316	REV: E2	SUN REV:	: Not In VersionControl
LAYER NAME = Bottom Layer				
TIDA-00316_E2.GBL	GENERATED : 6/12/2	2015 4:11:16	PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00316	REV: E2	SUN REU:	Not In VersionControl
LAYER NAME = Bottom Solder				
TIDA-00316_E2.GBS	GENERATED : 6/12/2	2015 4:11:17	PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00316	REV: E2	SUN REU:	Not In VersionControl
LAYER NAME = Bottom Overlay				
TIDA-00316_E2.GB0	GENERATED : 6/12/2	2015 4:11:17	PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00316	REV: E2	SUN REV	: Not In VersionControl
LAYER NAME = M1 Board Outline				
TIDA-00316_E2.GM1	GENERATED : 6/12/2	2015 4:11:17	PM	TEXAS INSTRUMENTS

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